Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D *** : Required Field**

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-10-26
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	LAURENT TOSI	Representative Title	MDG MD CHAMPION
Representative Phone *	33 442 685 795	Representative Email *	laurent.tosi@st.com
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

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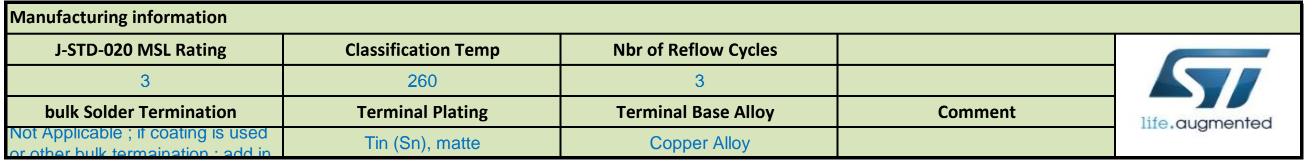
Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier’s liability and the Company’s remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	**Mfr Item Name**	**Version**	**Mfr Site**	**Date**
STM32H753BIT6	P1UH*450XXXV	A	9998	2018-10-26
	Amount	**UoM**	**Unit type**	**ST ECOPACK Grade**
	2240.00	mg	Each	ECOPACK® 2
,	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		



Manufacturing information				
J-STD-020 MSL Rating	**Classification Temp**	**Nbr of Reflow Cycles**		
3	260	3		
bulk Solder Termination	**Terminal Plating**	**Terminal Base Alloy**	**Comment**	
Not Applicable ; if coating is used or other bulk termaination ; add in	Tin (Sn), matte	Copper Alloy		

Package Designator	**Size**	**Nbr of instances**	**Shape**	
QFP	28x28x1.4	208	L bend	
Comment	Package: UH LQFP 208 28x28x1.4 1.0 7147657			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	**Response**
1 - Product(s) meets EU RoHS requirement without any exemptions	**TRUE**
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE

Exemption Id.	Description

QueryList : REACH-12th January 2017				
Query				**Response**
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				**true**
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						**Mfr Item Name**	**P1UH*450XXXV**					
Homogeneous Material	**Material Group**	**Mass**	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Die	Other inorganic materials	16.439	mg	supplier	die	Silicon (Si)	7440-21-3		15.697	mg	954863	7008
				supplier	metallization	Aluminium (Al)	7429-90-5		0.088	mg	5353	39
				supplier	metallization	Copper (Cu)	7440-50-8		0.276	mg	16789	123
				supplier	passivation	Nickel (Ni)	7440-02-0		0.001	mg	61	0
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.045	mg	2737	20
				supplier	metallization	Titanium (Ti)	7440-32-6		0.008	mg	487	4
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	61	0
				supplier	Passivation	Silicon Oxide	7631-86-9		0.323	mg	19648	144
LEADFRAME (MHT - C194)	Other inorganic materials	433.328	mg	supplier	ALLOY	Copper (Cu)	7440-50-8		422.278	mg	974500	188517
				supplier	ALLOY	Iron (Fe)	7439-89-6		10.400	mg	24000	4643
				supplier	ALLOY	Zinc (Zn)	7440-66-6		0.520	mg	1200	232
				supplier	ALLOY	Metallic Phosphorous (P)	7723-14-0		0.130	mg	300	58
LEADFRAME (MHT - Ag Plating)	Other inorganic materials	1.592	mg	supplier	COATING	Silver(Ag)	7440-22-4		1.592	mg	1000000	711
DIE ATTACH (Evertech - AP4200)	Other inorganic materials	2.572	mg	supplier	GLUE	Silver(Ag)	7440-22-4		2.006	mg	780000	896
				supplier	GLUE	Phenolic Resin	9003-35-4		0.039	mg	15000	17
				supplier	GLUE	Ethylene glycol monobutyl ether acetate	112-07-2		0.103	mg	40000	46
				supplier	GLUE	Polymer with oxirane and Phenol	9003-36-5		0.386	mg	150000	172
				supplier	GLUE	1,4-Butanedioldiglycidyl Ether	2425-79-8		0.039	mg	15000	17
BONDING WIRE (Heesung - Au HTS W	Other inorganic materials	5.680	mg	supplier	BONDING WIRE	Gold (Au)	7440-57-5		5.680	mg	999960	2536
				supplier	BONDING WIRE	Calcium (Ca)	7440-70-2		0.000	mg	40	0
BONDING WIRE (Heesung - Au HTS W	Other inorganic materials	0.057	mg	supplier	BONDING WIRE	Palladium (Pd)	7440-05-3		0.057	mg	1000000	25
ENCAPSULATION (Sumitomo -G631SH	Other inorganic materials	1768.981	mg	supplier	MOLDING COMPOUND	Epoxy Resin A	Trade secret		53.092	mg	30013	23702
				supplier	MOLDING COMPOUND	Epoxy resin B	85954-11-6		70.789	mg	40017	31602
				supplier	MOLDING COMPOUND	Silica Amorphous A (SiO3)	60676-86-0		1238.064	mg	699874	552707
				supplier	MOLDING COMPOUND	Silica Amorphous B (SiO3)	7631-86-9		274.307	mg	155065	122459
				supplier	MOLDING COMPOUND	Carbon Black	1333-86-4		8.849	mg	5002	3950
				supplier	MOLDING COMPOUND	Phenol Resin	205830-20-2		123.881	mg	70029	55304
FINISHING (Sytron - Sn100)	Other inorganic materials	11.350	mg	supplier	COATING	Tin (Sn)	7440-31-5		11.350	mg	1000000	5067